

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	9073	438/637-638,672-673,700,618-622. ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/06 09:51
L4	592	257/785.cccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/06 09:52
L5	9665	1 4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/06 09:53
L6	5062	5 and (dual adj damascene via trench) with (etch\$4 pattern\$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/06 09:56
L7	3249	6 and (dual adj damascene via trench) with (conduct\$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/06 09:57
L8	2247	7 and (resist photoresist) with (etch\$4 pattern\$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/06 09:56
L9	956	8 and (dual adj damascene via trench) with (conduct\$4) with interconnect\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/06 09:59

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Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L14	0	(dual adj damascene adj interconnect and substrate with first adj etched adj region and protective adj layer and coating with protective adj layer with resist adj layer and successively with patterning and opening and encompassing and recessed and second adj etched adj region and portion and conductive adj material and interconnect).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/06 10:31

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L10	94	9 and antireflect\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/06 10:00
L12	17	("6013581" "6057239" "6268283" "63 50681" "6365529" "6455416" "651486 0" "6861347" "6861347").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/06 10:05
L13	138	("6013581" "6057239" "6268283" "63 50681" "6365529" "6455416" "651486 0" "6861347" "6861347")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/06 10:05
L14	0	(dual adj damascene adj interconnect and substrate with first adj etched adj region and protective adj layer and coating with protective adj layer with resist adj layer and successively with patterning and opening and encompassing and recessed and second adj etched adj region and portion and conductive adj material and interconnect).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/02/06 10:31